

# MIC4467/8/9

# **Ouad 1.2A Peak Low-Side MOSFET Drivers**

#### **Features**

- Reliable, Low-Power Bipolar/CMOS/DMOS Construction
- Latch-Up Protected to >500 mA Reverse Current
- · Logic Input withstands Swing to -5V
- · High 3A Peak Output Current
- · Wide 4.5V to 18V Operating Range
- · Symmetrical Rise and Fall Times
- Short <40 ns Typical Delay Time</li>
- · TTL Logic Input Independent of Supply Voltage
- · Low Equivalent 6 pF Input Capacitance
- Low 5Ω Typical Output Impedance
- Output Voltage Swings within 25 mV of Ground or  $\rm V_S.$

#### **Applications**

- · General-Purpose CMOS Logic Buffer
- · Driving All 4 MOSFETs in an H-Bridge
- · Direct Small Motor Driver
- · Relay or Peripheral Drivers
- · Dual Differential Output Power Drivers
- · CCD Driver
- · Pin Switching Network Driver

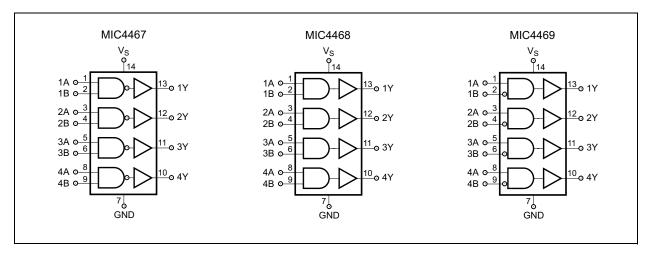
#### **General Description**

The MIC4467/8/9 family of four output CMOS buffer/drivers is an expansion from the earlier single-and dual-output drivers, to which they are functionally closely related. Because package pin count permitted it, each driver has been equipped with a dual input logic gate for added flexibility. Placing four high-power drivers in a single package also improves system reliability and reduces total system cost. In some applications, one of these drivers can replace not only two packages of single-input drivers, but some of the associated logic as well.

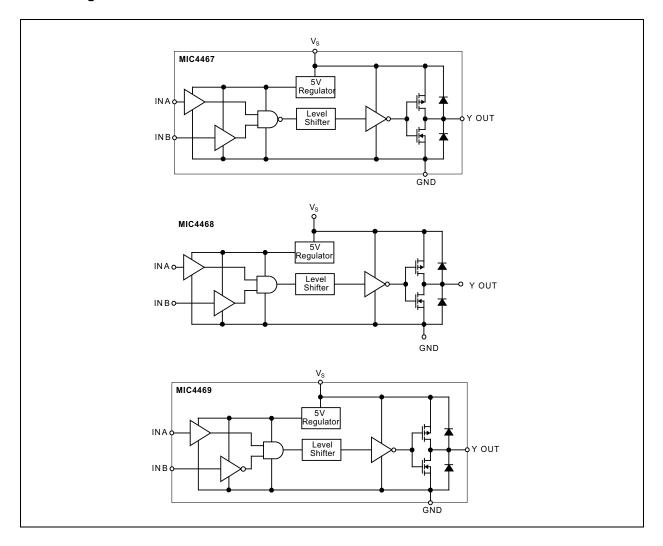
Although primarily intended for driving power MOSFETs, and similar highly capacitive loads, these drivers are equally well suited to driving any other load (capacitive, resistive, or inductive), which requires high efficiency, low-impedance driver capable of high peak currents, rail-to-rail voltage swings, and fast switching times. For example, heavily loaded clock lines, coaxial cables, and piezoelectric transducers can all be driven easily with MIC446x series drivers. The only limitation on loading is that total power dissipation in the IC must be kept within the power dissipation limits of the package.

The MIC446x series drivers are built using a BCD process. They will not latch under any conditions within their power and voltage ratings. They are not subject to damage when up to 5V of noise spiking (either polarity) occurs on the ground line. They can accept up to half an amp of inductive kickback current (either polarity) into their outputs without damage or logic upset.

# **Logic Diagrams**



# **Block Diagrams**



#### 1.0 ELECTRICAL CHARACTERISTICS

#### **Absolute Maximum Ratings †**

Supply Vo	oltage+	-22V
Input Volt	tageV <sub>S</sub> + 0.3V to GND	– 5V

#### **Operating Ratings ‡**

**† Notice:** Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability. Specifications are for packaged product only.

**‡ Notice:** The device is not guaranteed to function outside its operating ratings.

**Note 1:** Devices are ESD sensitive. Handling precautions are recommended. Human body model, 1.5 k $\Omega$  in series with 100 pF.

#### **ELECTRICAL CHARACTERISTICS**

Electrical Characteristics: Measured at T<sub>A</sub> = +25°C with 4.5V ≤ V<sub>S</sub> ≤ 18V unless otherwise specified. (Note 1)

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions	
Input							
Logic 1 Input Voltage	V <sub>IH</sub>	2.4	1.3	_	V	_	
Logic 0 Input Voltage	V <sub>IL</sub>	_	1.2	0.8	V	_	
Input Current	I <sub>IN</sub>	-1	_	1	μA	$0V \le V_{IN} \le V_{S}$	
Output							
High Output Voltage	V <sub>OH</sub>	V <sub>S</sub> - 0.15		_	V	I <sub>LOAD</sub> = 10 mA	
Low Output Voltage	V <sub>OL</sub>	_		0.15	V	I <sub>LOAD</sub> = 10 mA	
Output Resistance	R <sub>O</sub>	_	5	15	Ω	I <sub>OUT</sub> = 10 mA, V <sub>S</sub> = 18V	
Peak Output Current	I <sub>PK</sub>		1.2		Α	_	
Latch-Up Protection Withstand Reverse Current	1	>500		_	mA	_	
Switching Time							
Rise Time	t <sub>R</sub>	_	14	25	ns	Figure 1-1	
Fall time	t <sub>F</sub>	_	13	25	ns	Figure 1-1	
Doloy Timo	t <sub>D1</sub>	_	30	75	ns	Figure 1-1	
Delay Time	t <sub>D2</sub>	_	45	75	ns	Figure 1-1	
Power Supply							
Power Supply Current	I <sub>S</sub>	_	0.2	4	mA	_	

Note 1: Specification for packaged product only.

#### **ELECTRICAL CHARACTERISTICS**

**Electrical Characteristics:** Measured over operating temperature range with  $4.5V \le V_S \le 18V$  unless otherwise specified. (Note 1)

Symbol	Min.	Тур.	Max.	Units	Conditions			
Input								
$V_{IH}$	2.4	1.4	_	V	_			
$V_{IL}$	_	1.0	0.8	V	_			
I <sub>IN</sub>	-1	_	1	μA	$0V \le V_{IN} \le V_{S}$			
$V_{OH}$	V <sub>S</sub> - 0.3	_	_	V	I <sub>LOAD</sub> = 10 mA			
$V_{OL}$	_	_	0.3	V	I <sub>LOAD</sub> = 10 mA			
R <sub>O</sub>	_	7	30	Ω	I <sub>OUT</sub> = 10 mA, V <sub>S</sub> = 18V			
I <sub>PK</sub>	_	1.2	_	Α	_			
I	500	_	_	mA	_			
t <sub>R</sub>	_	17	50	ns	Figure 1-1			
t <sub>F</sub>	_	16	50	ns	Figure 1-1			
t <sub>D1</sub>	_	35	100	ns	Figure 1-1			
t <sub>D2</sub>	_	55	100	ns	Figure 1-1			
Power Supply								
I <sub>S</sub>	_	0.4	8	mA	_			
	V <sub>IH</sub> V <sub>IL</sub> I <sub>IN</sub> VOH VOL RO I <sub>PK</sub> I t <sub>R</sub> t <sub>F</sub> t <sub>D1</sub>	V <sub>IH</sub> 2.4 V <sub>IL</sub> — I <sub>IN</sub> —1  V <sub>OH</sub> V <sub>S</sub> -0.3 V <sub>OL</sub> — R <sub>O</sub> — I <sub>PK</sub> — I 500  t <sub>R</sub> — t <sub>F</sub> — t <sub>D1</sub> —	V <sub>IH</sub> 2.4 1.4 V <sub>IL</sub> — 1.0 I <sub>IN</sub> —1 —  V <sub>OH</sub> V <sub>S</sub> -0.3 — V <sub>OL</sub> — 7 I <sub>PK</sub> — 1.2 I 500 —  t <sub>R</sub> — 17 t <sub>F</sub> — 16 t <sub>D1</sub> — 35 t <sub>D2</sub> — 55	V <sub>IH</sub> 2.4         1.4         —           V <sub>IL</sub> —         1.0         0.8           I <sub>IN</sub> —1         —         1           V <sub>OH</sub> V <sub>S</sub> -0.3         —         —           V <sub>OL</sub> —         —         0.3           R <sub>O</sub> —         —         0.3           I <sub>PK</sub> —         1.2         —           I         500         —         —           t <sub>R</sub> —         17         50           t <sub>F</sub> —         16         50           t <sub>D1</sub> —         35         100           t <sub>D2</sub> —         55         100	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$			

Note 1: Specification for packaged product only.

# **TEMPERATURE SPECIFICATIONS (Note 1)**

Parameters	Symbol	Min.	Тур.	Max.	Units	Conditions		
Temperature Ranges								
Operating Ambient Temperature	т	-40	_	+85	°C	Temperature Range Device: Y		
Operating Ambient Temperature	T <sub>A</sub>	0	_	+70	°C	Temperature Range Device: Z		
Maximum Junction Temperature	T <sub>J</sub>	_	_	+150	°C	_		
Storage Temperature Range	T <sub>S</sub>	-65	_	+150	°C	_		
Lead Temperature	T <sub>LEAD</sub>	_	_	+300	°C	Soldering, 10 sec.		
Package Thermal Resistances								
Thermal Resistance 14-Lead PDIP	$\theta_{JA}$	_	80	_	°C/W	_		
Thermal Resistance 16-Lead Wide SOIC	$\theta_{JA}$	_	120	_	] C/VV	_		

Note 1: The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction to air (i.e.,  $T_A$ ,  $T_J$ ,  $\theta_{JA}$ ).

#### **Test Circuits**

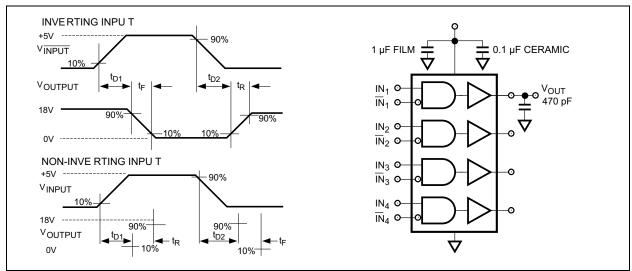


FIGURE 1-1: Inverting and Non-Inverting Input.

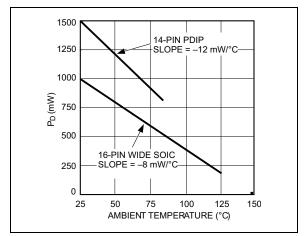
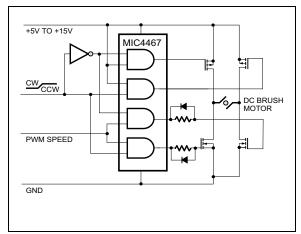


FIGURE 1-2: Package Power Dissipation.



**FIGURE 1-3:** Quad Driver Drives H Bridge to Control motor Speed and Direction.

#### 2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

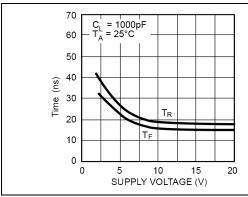


FIGURE 2-1: Rise and Fall Time vs. Supply Voltage.

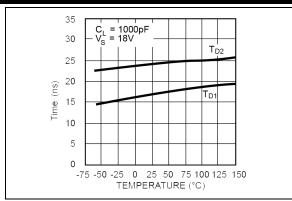


FIGURE 2-4: Delay Time vs. Temperature.

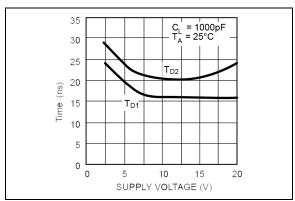


FIGURE 2-2: Delay Time vs. Supply Voltage.

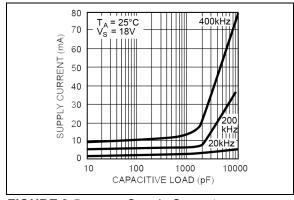


FIGURE 2-5: Supply Current vs. Capacitive Load.

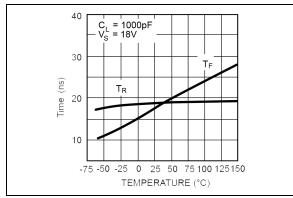


FIGURE 2-3: Temperature.



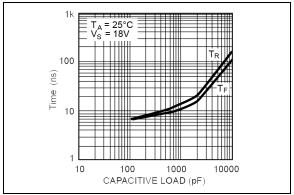


FIGURE 2-6:

Rise and Fall Time vs.

Capacitive Load.

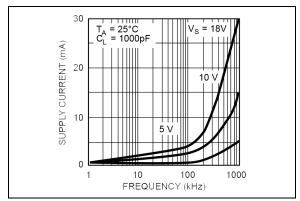


FIGURE 2-7: Frequency.

Supply Current vs.

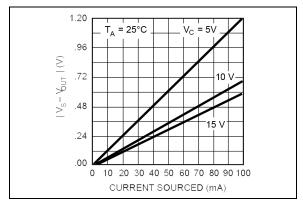


FIGURE 2-8:

High Output vs. Current.

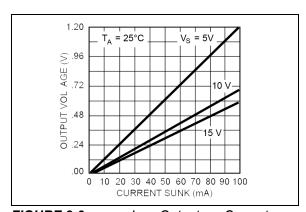
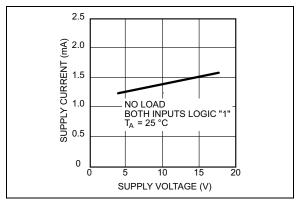


FIGURE 2-9:

Low Output vs. Current.



**FIGURE 2-10:** Quiescent Power Supply Current vs. Supply Voltage.

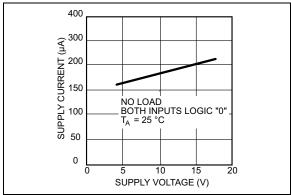
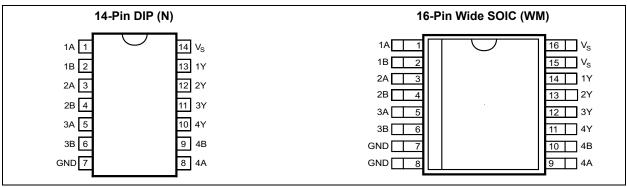


FIGURE 2-11: Quiescent Power Supply Current vs. Supply Voltage.

#### 3.0 PIN DESCRIPTIONS

# **Package Types**



The descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLE

IADLE 3-1.	FIN FUNCTION TABLE							
Pin Number DIP	Pin Number Wide SOIC	Pin Name	Description					
1	1	1A	Input A for Driver 1. TTL/CMOS Compatible Input					
2	2	1B	Input B for Driver 1. TTL/CMOS Compatible Input					
3	3	2A	Input A for Driver 2. TTL/CMOS Compatible Input					
4	4	2B	Input B for Driver 2. TTL/CMOS Compatible Input					
5	5	3A	Input A for Driver 3. TTL/CMOS Compatible Input					
6	6	3B	Input B for Driver 3. TTL/CMOS Compatible Input					
7	7	GND	Ground					
8	_	4A	Input A for Driver 4. TTL/CMOS Compatible Input					
_	8	GND	Ground					
9	_	4B	Input B for Driver 4. TTL/CMOS Compatible Input					
_	9	4A	Input A for Driver 4. TTL/CMOS Compatible Input					
10	_	4Y	Output for Driver 4, CMOS Push-Pull Output					
_	10	4B	Input B for Driver 4. TTL/CMOS Compatible Input					
11	_	3Y	Output for Driver 3, CMOS Push-Pull Output					
_	11	4Y	Output for Driver 4, CMOS Push-Pull Output					
12	_	2Y	Output for Driver 2, CMOS Push-Pull Output					
_	12	3Y	Output for Driver 3, CMOS Push-Pull Output					
13	_	1Y	Output for Driver 1, CMOS Push-Pull Output					
_	13	2Y	Output for Driver 2, CMOS Push-Pull Output					
14	_	VS	Supply Input, 4.5V to 18V					
	14	1Y	Output for Driver 1, CMOS Push-Pull Output					
	15	VS	Supply Input, 4.5V to 18V					
	16	VS	Supply Input, 4.5V to 18V					

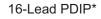
# 3.1 Truth Table

TABLE 3-2: TRUTH TABLE

Dord No.	Inp	Output	
Part No.	Α	В	Υ
	L	Х	Н
MIC4467 (Each Driver)	Х	L	Н
(Lacii Biivei)	Н	Н	L
14104400	Н	Н	Н
MIC4468 (Each Driver)	L	Х	L
(Lacii Biivei)	Х	L	L
14104400	L	Х	L
MIC4469 (Each Driver)	Х	Н	L
(Edon Briver)	Н	L	Н

#### 4.0 PACKAGING INFORMATION

#### 4.1 Package Marking Information

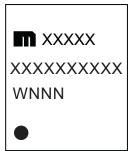




Example



16-Lead Wide SOIC\*



Example



**Legend:** XX...X Product code or customer-specific information

Y Year code (last digit of calendar year)
YY Year code (last 2 digits of calendar year)
WW Week code (week of January 1 is week '01')

NNN Alphanumeric traceability code

Pb-free JEDEC® designator for Matte Tin (Sn)

\* This package is Pb-free. The Pb-free JEDEC designator ((e3))

can be found on the outer packaging for this package.

•, ▲, ▼ Pin one index is identified by a dot, delta up, or delta down (triangle mark).

**Note**: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information. Package may or may not include the corporate logo.

Underbar (\_) and/or Overbar (¯) symbol may not be to scale.

**Note:** If the full seven-character YYWWNNN code cannot fit on the package, the following truncated codes are used based on the available marking space:

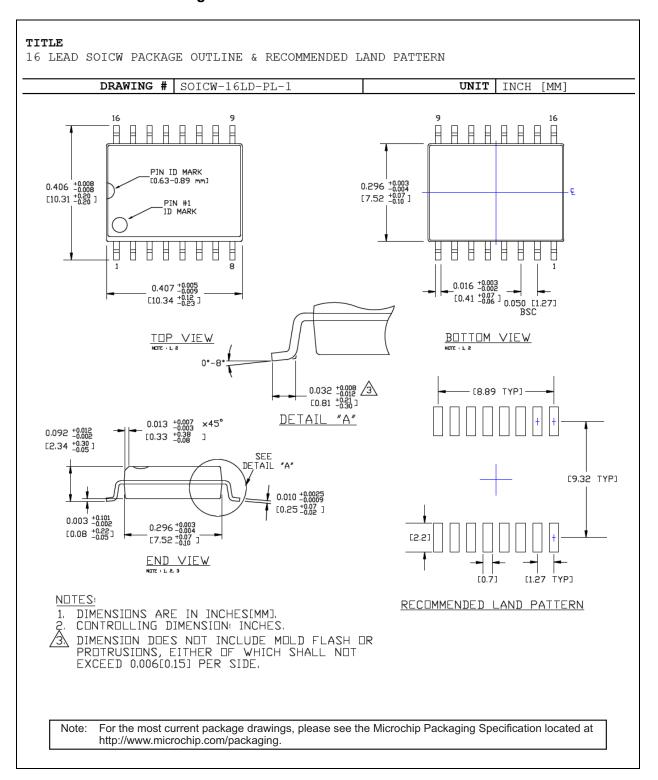
6 Characters = YWWNNN; 5 Characters = WWNNN; 4 Characters = WNNN; 3 Characters = NNN;

2 Characters = NN; 1 Character = N

# 14-Lead Plastic DIP Package Outline and Recommended Land Pattern

# TITLE 14 LEAD PDIP PACKAGE OUTLINE & RECOMMENDED LAND PATTERN DRAWING # PDIP-14LD-PL-1 UNIT INCH LEAD FRAME Copper LEAD FINISH Matte Tin Ø.080±.005 0.013DP MAX (3 PLACES) .005 MIN .130±.008 .310 BSC .015 GAGE PLANE .085±.020 .085±.020 150 MAX 125 MIN BASE MATERIAL Z 0.15 SECTION A-A .050 TYF For the most current package drawings, please see the Microchip Packaging Specification located at Note: http://www.microchip.com/packaging.

#### 16-Lead Wide SOIC Package Outline and Recommended Land Pattern



#### **APPENDIX A: REVISION HISTORY**

# Revision A (May 2022)

- Converted Micrel document MIC4467/8/9 to Microchip data sheet DS20006614A.
- Minor text changes throughout.

MI	<b>C44</b>	67	18	/9
	$oldsymbol{oldsymbol{ a}}$	~		•

NOTES:

# PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

PART NO.	X	XX	–XX	Examples	:	
Device	Temperature Range	Package	Media Type	a) MIC4467:		1.2A-Peak, Quad Low-Side MOSFET Driver, NAND Input Logic, -40°C to +85°C Industrial Temperature Range, RoHS Compliant
				MIC4467YWI	М	16-Lead SOIC Wide Package, 47/Tube
	MIC4467:	Quad 1.2A-Peak Low-	Side MOSFET Driver	MIC4467YWI	M-TR	16-Lead SOIC Wide Package, 1,000/Reel
	MIC4468:	with Bi-Polar/CMOS/E ing NAND Input Logic Quad 1.2A-Peak Low-		b) MIC4467:		1.2A-Peak, Quad Low-Side MOSFET Driver, NAND Input Logic, 0°C to +70°C Commercial Temperature Range, RoHS Compliant
Device:		with Bi-Polar/CMOS/E	OMOS Process	MIC4467ZN		14-Lead PDIP Package, 25/Tube
		featuring AND Input L	ogic	MIC4467ZWI	М	16-Lead SOIC Wide Package, 47/Tube
	MIC4469:	Quad 1.2A-Peak Low-	-Side MOSFET Driver	MIC4467ZWI	M-TR	16-Lead SOIC Wide Package, 1000/Reel
		DMOS Process nverting Input Logic	c) MIC4468:		1.2A-Peak, Quad Low-Side MOSFET Driver, AND Input Logic, –40°C to +85°C Industrial Temperature Range, RoHS Compliant	
Temperature Range:	Y =	-40°C to +85°C, Indus	strial	MIC4468YN		14-Lead PDIP Package, 25/Tube
	Z =	(RoHs Compliant) 0°C to +70°C, Comme	ercial	MIC4468YWI	М	16-Lead SOIC Wide Package, 47/Tube
		(RoHs Compliant)		MIC4468YWI	M-TR	16-Lead SOIC Wide Package, 1,000/Reel
Package:	N = WM =	14-Lead PDIP 16-Lead SOIC (Wide I	Body)	d) MIC4468:		1.2A-Peak, Quad Low-Side MOSFET Driver, AND Input Logic, 0°C to +70°C Commercial Temperature Range, RoHS Compliant
				MIC4468ZN		14-Lead PDIP Package, 25/Tube
Media Type:	<blank> =</blank>	25/Tube (N, PDIP)		MIC4468ZWI	М	16-Lead SOIC Wide Package, 47/Tube
1		47/Tube (WM, SOIC)	íC)	MIC4468ZWI	M-TR	16-Lead SOIC Wide Package, 1,000/Reel
	TR = 1,000/Reel (WM,	1,000/Reel (WM, SOIC		MIC4469:		1.2A-Peak, Quad Low-Side MOSFET Driver, AND with 1 Inverting Input Logic, -40°C to +85°C Industrial Temperature Range, RoHS Compliant
				MIC4469YN		14-Lead PDIP Package, 25/Tube
				MIC4469YWI	М	16-Lead SOIC Wide Package, 47/Tube
				MIC4469YWI	M-TR	16-Lead SOIC Wide Package, 1,000/Reel
				MIC4469:		1.2A-Peak, Quad Low-Side MOSFET Driver, AND with 1 Inverting Input Logic, -40°C to +85°C Commercial Temperature Range, RoHS Compliant
				MIC4469ZN		14-Lead PDIP Package, 25/Tube
				MIC4469ZWI	М	16-Lead SOIC Wide Package, 47/Tube
				MIC4469WM	-TR	16-Lead SOIC Wide Package, 1,000/Reel
				t c	oart number o ordering purp oackage. Che	el identifier only appears in the catalog description. This identifier is used for oses and is not printed on the device eck with your Microchip Sales Office for lability with the Tape and Reel option.

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NOTES:

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